

TEST RESULTS CONCERNING PLASTI DIP CHEMICAL RESISTANCE

<u>CHEMICALS USED</u>	<u>STRENGTH</u>	<u>TEMPERATURE</u>	<u>RESISTANCE</u>
Ferric Chloride	100%	150 degrees F.	Slight staining and softness of film
H2SO4	5%	100 degrees F.	Pass
Potassium Hydroxide	3%	150 degrees F.	Pass
Potassium Permanganate	3%	150 degrees F.	Film stable – noticed staining
Sodium Hydroxide	10%	210 degrees F.	Noticed softness of film
Hydrochloric Acid	100%	Room Temp	Pass
Oxalic Acid	50%	Room Temp	Film stable in chemical / water solution
Fluoroboric Acid	25%	Room Temp	Pass
Tin/Lead – salt plating solution	100%	Room Temp	Pass
Copper – salt plating solution	100%	Room Temp	Pass
Gold Cyanide – plating solution	100%	140 degrees F.	Pass
Sodium Carbonate	10%	210 degrees F.	Pass
Sodium Hydroxide	10%	120 degrees F.	Noticed softness of film
Ammonia Hydroxide	100%	100 degrees F.	Pass
Methyl Ethyl Ketone	100%	Room Temp	Fail
Ethyl Alcohol	100%	Room Temp	Pass